

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Akram et al.

Serial No.: 09/832,160

Filed: April 9, 2001

For: WAFER-LEVEL PACKAGE AND
METHODS OF FABRICATING

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Group Art Unit: 2822

Attorney Docket No.: 2269-3846.2US
(98-0796.02/US)

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June 11, 2007

**FEE ADDRESSEE FOR RECEIPT OF PTO NOTICES
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Sir:

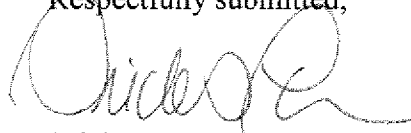
1. This letter is to specify that the FEE ADDRESSEE for this patent is:

MICRON TECHNOLOGY, INC.
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Serial No.: 09/832,160

2. The Customer Number for the Fee Addressee is **26809**.
3. Any prior FEE ADDRESSEE for this patent is hereby revoked.
4. It is certified that the person whose signature appears below has the authority to change the FEE ADDRESSEE for this patent.

Respectfully submitted,



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